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(0) ((( (((wafer and (interconnect or (inter adj
(48) ((( (((wafer and (interconnect or (inter adj
(5) ("5640327" | "5822214" | "6260183" | "6324674"
(1) 6412097.URPN.
(0) ((wafer and (interconnect or (inter adj connec
(1) Manhattan adj direction
(34) Manhattan with direction
(21) (Manhattan with direction) and interconnect$4
(16) ((Manhattan with direction) and interconnect$4
(7) ("4805113" | "5340772" | "5341024" | "5532934"
(5) ((Manhattan with direction) and interconnect$4
(99) (complement$4 with (wiri$4 adj layer))
(72) (((complement$4 with (wiri$4 adj layer))) and
(6) (((complement$4 with (wiri$4 adj layer))) and
(66) (((complement$4 with (wiri$4 adj layer))) and
(55) (((((complement$4 with (wiri$4 adj layer))) and
(51) ((((((complement$4 with (wiri$4 adj layer)))) and
(51) (((((((complement$4 with (wiri$4 adj layer)))) and

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DBs	USPAT, US-PGPUB, EPO, JPO, IBM, TDB		
Default operator	OR		
<input type="checkbox"/> Plurals <input type="checkbox"/> Highlight all hit terms initially			
(((complement\$4 with (wiri\$4 adj layer))) and direction) and diagonal			

	U	C	PT	P	Document ID	Issue Date	Pages	Title	Current OR	Current XR	Retrieval	Inventor	S	C	Image D
1	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6526555	20030225	60	Method for layout and manufacture of gridless Resin-encapsulated semiconductor apparatus	716/11	716/12; 716/13; 257/787		Teig, Steven et al.	<input type="checkbox"/>	<input type="checkbox"/>	US 6526
2	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	20020195725	20021226	25	Resin-encapsulated semiconductor apparatus	257/792			Tanaka, Jun et al.	<input type="checkbox"/>	<input type="checkbox"/>	US 2002019
3	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	20020195724	20021226	25	Resin-encapsulated semiconductor apparatus	257/792			Tanaka, Jun et al.	<input type="checkbox"/>	<input type="checkbox"/>	US 2002019
4	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	20020060373	20020523	26	Resin-encapsulated semiconductor apparatus	257/792			Tanaka, Jun et al.	<input type="checkbox"/>	<input type="checkbox"/>	US 2002006
5	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	20020027268	20020307	25	Resin-encapsulated semiconductor apparatus	257/666	257/787; 257/792		Tanaka, Jun et al.	<input type="checkbox"/>	<input type="checkbox"/>	US 2002002
6	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 5005068	19910402	21	Semiconductor memory device	365/154	257/904; 257/906;		Ikeda, Shuji et al.	<input type="checkbox"/>	<input type="checkbox"/>	US 5005